


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F303CBT7	S65B*422XXXY	A	998Z	22-09-2017
	Amount	UoM	Unit type	ST ECOPACK Grade
	183.48	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7X7X1.4	48	L Bend	
Comment	Package : 5B LQFP 48 7x7x1.4 1 0110596			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH- 7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	S65B*422XXXY				5.999999.0	0.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	18.418	mg	supplier	die	Silicon (Si)	7440-21-3		17.666	mg	959170	96285
				supplier	metallization	Aluminium (Al)	7429-90-5		0.051	mg	2769	278
				supplier	metallization	Copper (Cu)	7440-50-8		0.255	mg	13845	1390
				supplier	metallization	Cobalt (Co)	7440-48-4		0.048	mg	2606	262
				supplier	metallization	Titanium (Ti)	7440-32-6		0.014	mg	760	76
				supplier	metallization	Tungsten (W)	7440-33-7		0.028	mg	1520	153
				supplier	Passivation	Silicon Nitride	12033-89-5		0.033	mg	1792	180
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	17537	1760
				Supplier	Metals	Silver	7440-22-4		2.131	mg	901000	11617
Die Attach Epoxy_ABLEBOND 3230_H	M-011 Other inorganic materials	2.366	mg	Supplier	Plastics/polymers	Highly cross-linked polymer	Proprietary		0.234	mg	99000	1276
Mold Compound_EME-G631SHQ_Sur	M-011 Other inorganic materials	107.476	mg	Supplier	Plastics/polymers	Epoxy Resin A	Proprietary		2.273	mg	21000	12387
				Supplier	Plastics/polymers	Epoxy Resin B	Proprietary		2.273	mg	21000	12387
				Supplier	Plastics/polymers	Phenol Resin	Proprietary		6.061	mg	56000	33033
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		83.715	mg	780450	-543730
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		12.481	mg	115320	68024
Wire_AG Si TYPE_MKE	Bonding Wire	0.260	mg	Supplier	Non-metals	Carbon Black	1333-86-4		0.674	mg	6230	3675
				Supplier	Metals	Silver	7440-22-4		0.250	mg	960000	1361
Plating anode_Pure Tin_Nuo Nengda	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Others	Proprietary		0.010	mg	40000	57
				Supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	5878
Leadframe_C194+Ag_MITSUI	Copper & its alloys	53.878	mg	Supplier	Metals	Copper	7440-50-8		51.814	mg	961700	282404
				Supplier	Metals	Iron	7439-89-6		1.223	mg	22700	6666
				Supplier	Metals	Zinc	7440-66-6		0.081	mg	1500	440
				Supplier	Non-metals	Phosphorus	7723-14-0		0.016	mg	300	88
				Supplier	Metals	Silver	7440-22-4		0.744	mg	13800	4052